

Title (en)

METHODS FOR WET PROCESSING ELECTRONIC COMPONENTS HAVING COPPER CONTAINING SURFACES

Title (de)

VERFAHREN ZUR NASSBEHANDLUNG VON ELEKTRONISCHEN BAUTEILEN MIT KUPFERENTHALTENDEN OBERFLÄCHEN

Title (fr)

PROCEDE DE TRAITEMENT PAR VOIE HUMIDE DE COMPOSANTS ELECTRONIQUES DONT LES SURFACES CONTIENNENT DU CUIVRE

Publication

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Application

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Abstract (en)

[origin: WO0071782A1] The present invention provides methods of wet processing electronic components having surfaces containing copper. In the methods of the present invention, copper containing electronic components are contacted with a copper oxidizing solution containing an oxidizing agent, and subsequently contacted with an etching solution. The methods of the present invention are particularly useful for cleaning copper containing components.

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